

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231**

Inventor: **Zhang, et al.**

Serial No: **Div. of 10/145649**

Filed: **May 14, 2002**

For: **Chemical Mechanical  
Planarization of Low  
Dielectric Constant Materials**

Examiner: **M. Anderson**

Art Unit: **1765**

**PRELIMINARY AMENDMENT**

Box Patent Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Please enter the following preliminary amendment:

**IN THE CLAIMS**

Please cancel all pending claims and add the following claims addressing subject matter in application serial number 10/145649:

20. (Added) A method of planarizing a low dielectric constant surface, comprising:

performing a conventional chemical mechanical planarization; and

buffing with an abrasive slurry, wherein the abrasive slurry comprises a plurality of core particles, wherein each core particle comprises a surface and at least one core particle at least one polymer core material; and a coating material that coats the surface of the plurality of core particles, wherein the core particles and the coating material form a plurality of abrasive particles and wherein the density of the coating material is less than the density of the core material.